

A

B

C

D

E

F

A

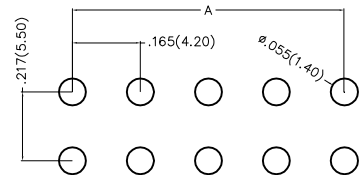
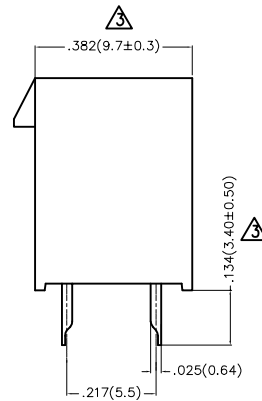
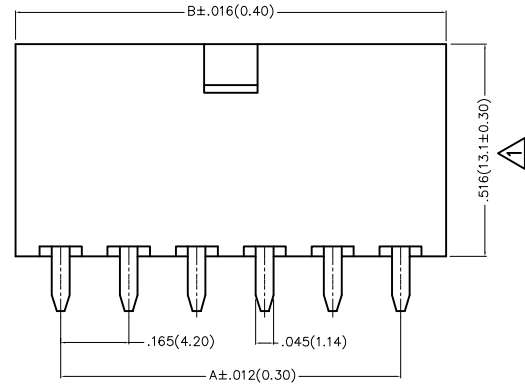
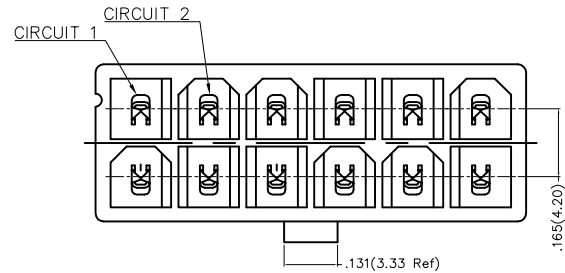
B

C

D

E

F



Recommended P.C.Board Layout

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Dimension: Change 12.95 into 13.10±0.30mm	26/SEP/18	KATE	FRANK
2		Flammability Change	02/AUG/23	MATT	LEO
3		Update Structure and Dimensions	02/AUG/23	MATT	LEO

Electrical

Current Rating: 7A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 15 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1500V AC r.m.s
Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA66 (UL 94V-2) Transparent
PA66 (UL 94V-0) White/Black
Contact Pin: Brass
Plating: Tin Plated

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF42001-D02S22XK	—	.220(5.60)
4	FWF42001-D04S22XK	.165(4.20)	.386(9.80)
6	FWF42001-D06S22XK	.331(8.40)	.551(14.00)
8	FWF42001-D08S22XK	.496(12.60)	.717(18.20)
10	FWF42001-D10S22XK	.661(16.80)	.882(22.40)
12	FWF42001-D12S22XK	.827(21.00)	1.047(26.60)
14	FWF42001-D14S22XK	.992(25.20)	1.213(30.80)
16	FWF42001-D16S22XK	1.157(29.40)	1.378(35.00)
18	FWF42001-D18S22XK	1.323(33.60)	1.543(39.20)
20	FWF42001-D20S22XK	1.488(37.80)	1.709(43.40)
22	FWF42001-D22S22XK	1.654(42.00)	1.874(47.60)
24	FWF42001-D24S22XK	1.819(46.20)	2.039(51.80)

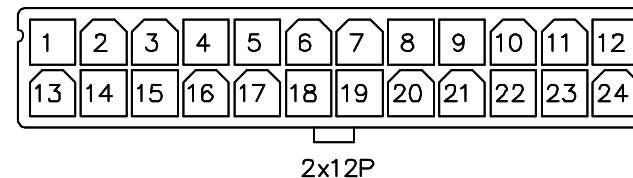
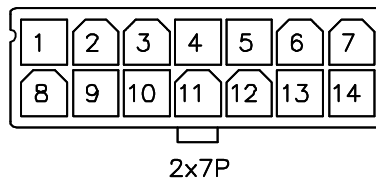
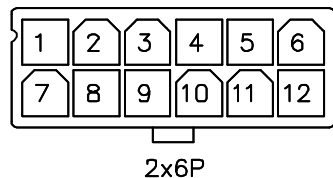
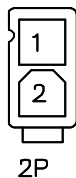
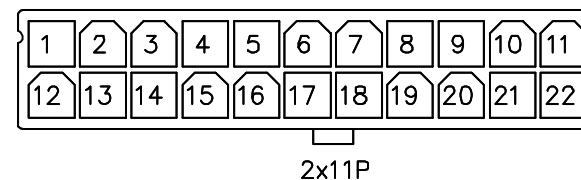
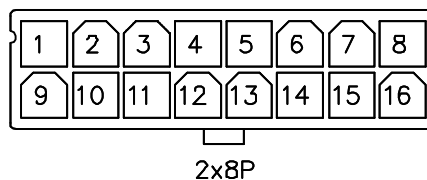
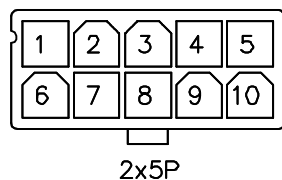
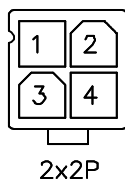
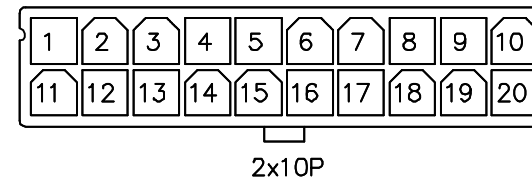
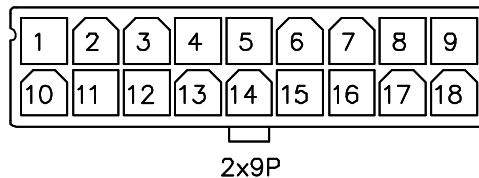
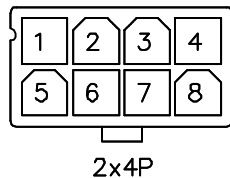
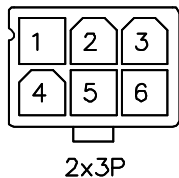
Ordering Information

FWF 420 01 — D XX S 2 2 X K
1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 420—Pitch4.2mm	3	Distinction No. 01	4	Row Option D—Double Row	5	Circuits XX	6	Entry Angle S—180° Vertical
7	Plating 2—Tin Plated	8	Material—Resin 2—PA66	9	Color—Resin T—Transparent W1—White K6—Black	10	Packaging K—Tray				

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF42001-DXXS22XK	ITEM NO. FWF42001	 Building Technology Cornerstone	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	.X'±2"	JACOB	28/JUN/13	Wire to Board (Wafer) Pitch 4.2mm 180° Vertical (DIP)		REV 3	SHEET NO. 1/2
		X.XX±.006(0.15)	.XX'±1"	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
SCALE 5:1	SIZE A4	X.XXX±.004(0.10)	.XXX'±0.5°	CHERRY	28/JUN/13				

Circuit Size Layout



THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF42001-DXXS22XK	ITEM NO. FWF42001	Building Technology Cornerstone
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.X±.008(0.20)	X.±5° .X°±2°	CHECKED BY JACOB	DATE 28/JUN/13	TITLE Wire to Board (Wafer) Pitch 4.2mm 180° Vertical (DIP)	
	SCALE 5:1	X.XX±.006(0.15) X.XXX±.004(0.10)	.XX°±1° .XXX°±0.5°	DRAWN BY CHERRY	DATE 28/JUN/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
	SIZE A4					REV 3 SHEET NO. 2/2	